

IN THE SPECIFICATION

Please insert the following sentence at page 1, between lines 3 and 4 (directly beneath the title):

The present application is a national stage application of International Application No. PCT/JP04/06437, filed on May 13, 2004, which published as WO 04/101248 on November 25, 2004, and claims priority to Japanese Application No. 02/09727, filed on May 13, 2003, the entire contents of which are hereby incorporated by reference.

Please amend paragraph [0029] as follows:

In addition, since the constituent composition between the above aluminum and the electroconductive metal continuously varies from the front face toward the back face in the thus constructed resin-forming mold, the above aluminum which constitutes the above front face together with oxygen is hardly separated from the above electroconductive film.

[Summary of the Invention]

Please amend paragraph [0101] as follows:

As shown in Figs. 6(a) to 6(c), the master plate S is a master plate having a pattern which forms a plurality of fine ~~depressions L~~ projections M on a surface of a stamper formed thereby.

Please amend Table 1 at page 17, paragraph [0117] as follows:

Table 1

	10 sec.	15 sec.	20 sec.	25 sec.	30 sec.	35 sec.
Example 1-1 (Stamper 10K)	×	○	○	○	○	○
<u>Comparative Example 1-1</u> [[2]] (Stamper 1K)	×	×	×	×	○	○
<u>Comparative Example 1-2</u> [[1]] (Stamper 10S)	×	×	×	○	○	○
Comparative Example 1-2 (Stamper 1S)	×	×	×	×	×	○

Please amend paragraph [0139] as follows:

(5) Examples 4-1 to 4-3

A stamper of A-type was fitted to a fixing side of the planar mold of 370 x 300 mm x 8 mm, and a stamper of B-type was fitted to a movable side thereof. Injection molding was carried out by using PMMA ("PARAPET" GH-1000S manufactured by Kuraray Co., Ltd), while the ~~holding pressure~~ cooling time was varied, so the relationship between the cooling time period and the mold releasability was examined. The mold releasability was evaluated according to results on whether the molded product could be taken out by the automatic takeout device or not. The injection molding condition and test results are shown in Table 7. The molded product could be excellently taken out in the practical conditional range.

Please amend Table 8 at page 27 as follows:

Relationship between the cooling time period and whether the mold-released mark was formed or not

	Used material	Kind of Stamper						Cooling time period (MPa)					
		Mold fixed side			Mold-movable side								
		Constituent composition of evaporated material (wt%)			Constituent composition of evaporated material (wt%)								
		Al	Ni		Al	Ni							
Example 5-1	PARAPET GH-1000S	B-3	70	30	C-3	70	30	Δ	○	◎	◎		
Example 5-2	PARAPET GH-1000S	B-4	30	70	C-4	30	70	×	Δ	○	◎		
Example 5-3	PARAPET GH-1000S	B-5	10	90	C-5	10	90	×	Δ	○	◎		
Example 6-1	MS resin TX	B-3	70	30	C-3	70	100	×	○	◎	◎		
Example 6-2	MS resin TX	B-4	30	70	C-4	30	100	×	Δ	◎	◎		
Comparative Example 5-1	PARAPET GH-1000S	B-6	0	100	C-6	0	100	×	×	Δ	○		
Comparative Example 6-1	PARAPET GH-1000S MS resin TX	B-6	0	100	C-6	0	100	×	×	×	○		

Note 1) Injection molding condition

Thickness of planar molded product: 8 mm, cylinder temperature: 265°C, mold temperature: 85°C, pressure-holding time period: 35 seconds, holding pressure: 30 MPa, filling time period: 9 seconds

2) ◎ “no mold-released mark”, ○ “slight mold-released mark”, Δ “mold-released mark”, and

× “conspicuous mold-released mark”